Design and Analysis of Low Power Generic Circuits in Nano Scale Technology

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Abstract

Power consumption of Very Large Scale Integrated (VLSI) circuits has been growing at an alarmingly rapid rate. This increase in power consumption, coupled with the increasing demand for portable/hand-held electronics, has made power consumption a dominant concern in the design of VLSI circuits today. Traditionally dynamic (switching) power has dominated the total power consumption of VLSI circuits. However, due to process scaling trends, leakage power has now become a major component of the total power consumption in VLSI circuits. Based on the International Technology Roadmap for Semiconductors (ITRS) report, the sub-threshold leakage power dissipation of a chip may exceed dynamic power dissipation at the 65nm feature size.

A new approach is considered to reduce leakage power in VLSI design; named as "SLEEPY KEEPER". Dual Vth values can be applied to sleepy keeper in order to dramatically reduce sub threshold leakage current. For applications spending the vast majority of time in sleep or standby mode requires low area, high performance and maintenance of exact logic state, the sleepy keeper approach provides a new weapon. SLEEPY KEEPER approach is applied to generic logic circuits and obtained results are compared with well established leakage **current reduction techniques like SLEEP, STACK, ZIGZAG, SLEEPY-STACK approaches.**

Index Terms: sleepy keeper, leakage power, delay.

Introduction

Digital integrated circuits are found everywhere in modern life and many of them are embedded in mobile devices where limited power resource is available (e.g. mobile phones, watches, mobile computers...). To permit a usable battery runtime, such devices must be designed to consume the lowest possible power. Reduced power consumption can highly decrease the packaging costs and highly increase the circuit reliability, which is tightly related to the circuit working temperature. In order to achieve high density and high performance, CMOS technology feature size and threshold voltage have been scaling down for decades. The reduction of the supply voltage is dictated by the need to maintain the electric field constant on the ever shrinking gate oxide. So, as the feature size becomes smaller, shorter channel lengths result in increased sub-threshold leakage current through a transistor when it is off. Low threshold voltage also results in increased sub-threshold leakage current because transistors cannot be turned off completely [1]. For these reasons, static power consumption, i.e., leakage power dissipation, has become a significant portion of total power consumption for current and future silicon technologies. There are several VLSI techniques namely SLEEP, STACK, ZIGZAG, SLEEPY-STACK approaches to reduce leakage power.

In "Sleep Approach "the transistors gating VDD and GND are added to the base case, the added transistors (Sleep transistors) turn off the circuit by cutting off the power rails when the logic circuit is not in use and thus can reduce leakage power effectively [2-3]. However, the output will be floating after sleep mode, so the technique results in destruction of state plus a floating output voltage. To reduce the wake-up cost of the sleep transistor technique, the "Zigzag Approach" is introduced [4]. By placing alternating sleep transistors based on which particular network is off for a specific set input vectors, the zigzag approach reduces wake-up cost but still it loses state. This approach may need extra circuitry to generate a specific input vectors.

In the "Stack Approach", every transistor in the base case network is duplicated with both original and duplicate bearing half the original transistor width [5]. Duplicated transistors cause a slight reverse bias between the gate and source when both transistors are turned off as a result a substantial current reduction is obtained. However because of increase in number of transistors delay significantly increases which limits the usefulness of the approach. The "Sleepy Stack Approach" has a structure combining the stack and sleep approaches by dividing every transistor into two transistors of half width and placing a sleep transistor in parallel with one of the divided transistor [6]. The stacked transistors suppress leakage current while saving state and the sleep transistor placed in parallel to the one of the stacked transistors, reduces resistance of the path, so delay is decreased during active mode. However, since every transistor is replaced by three transistors, area penalty is a significant matter for this approach.

Each technique provides an efficient way to reduce leakage power, but disadvantages of each technique limit the application of each technique. A new approach called "Sleepy Keeper approach" is proposed for low-leakage power VLSI design [7]. The Sleepy Keeper has a novel structure that reduces leakage current while saving exact logic state. Sleepy keeper uses traditional sleep transistors plus two additional transistors driven by a gate's already calculated output to save state during sleep mode. Also, Dual-Vth values can be applied to sleepy keeper in order to

dramatically reduce sub-threshold leakage current. Like the sleepy stack approach, sleepy keeper achieves leakage power reduction equivalent to the sleep and zigzag approaches but with the advantage of maintaining exact logic state.

Proposed Approach: Sleepy Keeper

The structure of the proposed sleepy keeper approach is shown in the figure 1 below. The basic problem with traditional CMOS is that the transistors are used only in their most efficient, and naturally inverting, way: namely, PMOS transistors connect to VDD and NMOS transistors connect to GND. It is well know that PMOS transistors are not efficient at passing GND and NMOS transistors are not efficient at passing VDD.



Figure 1: Sleepy keeper approach.

From the figure1 it is observed that there is a sleepy keeper PMOS transistor connecting GND to the pull-down network. When in sleep mode, this PMOS transistor is the only source of GND since the sleep transistor is off. On the other hand, there is an additional single NMOS transistor connecting VDD to the pull-up network and during sleep mode, NMOS transistor is the only source of VDD.

Operation

To maintain a value of '1' in sleep mode, given that the '1' value has already been calculated, the sleepy keeper approach uses this output value of '1' and an NMOS

transistor connected to VDD to maintain output value equal to '1' when in sleep mode. Consider the case when the output is '1' for an inverter designed utilizing the sleepy keeper approach, the current path is shown in Figure 2a.



Figure 2: "Sleepy Keeper" Approach (SLEEP MODE).

Similarly, to maintain a value of '0' in sleep mode, given that the '0' value has already been calculated, the sleepy keeper approach uses this output value of '0' and a PMOS transistor connected to GND to maintain output value equal to '0' when in sleep mode. The case when the output is '0' for an inverter implemented using the sleepy keeper approach, the current path is shown in Figure 2b. For sleepy keeper approach to work, it is needed, to connect NMOS to VDD and the PMOS to GND to maintain proper logic state. This seems possible as other researchers have described ways to use far lower VDD values to maintain logic state.

Experimental Methodology

Schematics and layouts are being designed for Sleep, Zigzag, Stack, Sleepy Stack and Sleepy Keeper, along with base case (conventional) using Tanner Tools [8] and Microwind [9]. Schematics are used to obtain net lists of test circuits, and the net lists are used to simulate and test the performance. Layouts are used to measure and predict area usage. The Experimental methodology is shown in figure 3.

Schematics are to be created based on BPTM 180nm process parameters. The schematics for the 3 test circuit's i.e. Chain of 4 Inverters, 4:1 Multiplexer, 4 bit adder is chosen as shown in figure 4.Net lists of test circuits for different techniques are to be extracted from the schematics. The net lists are to be modified to fit into all technologies using the 180nm process as well for 90nm, 65nm and 45nm processes. Synopsys HSPICE [10] simulation is used to estimate propagation delay and power consumption. All considered approaches are to be evaluated for performance by using a single, low-Vth for all transistors. Dual Vth technology is applied and tested for sleepy stack and sleepy keeper approaches. For the dual Vth technique, high-Vth is used for leakage reduction transistors and low-Vth is used for the other transistors. For the sleepy stack and sleepy keeper approaches, every sleep transistor and any

transistor parallel to the sleep transistor are configured as high-Vth transistors. The high-Vth is set to have 2.0 times higher Vth than the Vth of a normal transistor [11]. Before running HSPICE, the net lists are modified to distinguish two different Vth values.



Figure 3: Experimental Methodology



Figure 4a: Chain of 4 Inverters



Figure 4b: 4:1 Multiplexer



Figure 4c: 1bit adder circuit

Worst case delay, static power consumption, dynamic power consumption and area for all the approaches are measured as follows.

Delay: Worst case propagation delay is measured for each approach. Input vectors and input/output triggers are chosen to measure the delay of a critical path. The propagation delay is measured from the trigger input edge reaching 50% of the supply voltage to the circuit output edge reaching 50% of the supply voltage value.

Static Power: Static power is measured by asserting sets of input vectors in HSPICE. The average power dissipation over the specific subset of input combinations chosen is determined as the static power.

Dynamic Power: For dynamic power measurement, clocked semi-random input vectors for a number of clock cycles are asserted, and average power dissipation during this time reported by HSPICE is considered as dynamic power consumption.

Area: Layouts for all the considered approaches are designed $0.18\mu m$ process by using Microwind software. Areas for below $0.18\mu m$ technology are estimated by scaling the area of each approach layout designed based on $0.18\mu m$ process.

Experimental Results

Impact of Vth and transistor width for Chain Of Inverters

Impact of Vth

Choosing the right Vth value of the sleepy keeper technique is very important in terms of delay and power consumption. Therefore, using a chain of 4 inverters with 65nm technology, dynamic power, static power and delay of the state-saving techniques are been compared, i.e., base case, stack, sleepy stack and sleepy keeper, while varying Vth. Vth of transistors is varied as follows: all the transistors in the base case; one of stacked transistors in the forced stack case; and the sleep transistors plus transistors parallel to the sleep transistors in the sleepy stack and sleepy keeper case. Figure 5 and 6 shows the measured results while varying Vth at 27° C and 110° C respectively. From Figure 5(a), it could be seen that stack inverter increases delay dramatically as Vth increases. The base case also shows relatively large variation compared to the sleepy keeper technique as Vth changes.

While varying Vth at 27° C, the sleepy keeper with Vth = 0.36V has almost exactly the same delay as the forced stack with Vth = 0.22V. Also, at 110° C, the sleepy keeper with Vth = 0.37V has exactly the same delay as the forced stack with Vth = 0.22V. At 27° C, the sleepy keeper with Vth=0.36V has the same delay as the base case with Vth=0.36V, and, at 110° C, the sleepy keeper with Vth=0.37V has the same delay as the base case with Vth=0.37V while the sleepy keeper achieves 2.3 times and 2.5 times leakage reduction, respectively.

From Figure 6(b), it was observed that the base case with Vth = 0.2V consumes unacceptable active power consumption when the temperature is 110° C. This is because large leakage power consumption of the base case severely hurts active power consumption. This result emphasizes the importance of the leakage power reduction techniques in nanoscale technology.



Figure 5: Results for Chain of 4 Inverters at 270C, Varying Vth a) Delay b) Static Power c) Dynamic Power



Figure 6: Results for Chain of 4 Inverters at 1100C, Varying Vth a) Delay b) Static Power c) Dynamic Power .

Impact of Transistor Width

The Vth of the base case, the sleepy stack and sleepy keeper technique is set to Vth = 0.44V and for the stack technique Vth is set 0.22V. Since the stack technique with high-Vth increases delay dramatically and the temperature is set to $27^{\circ}C$. The results show that inverter chain delay decreases as transistor width increases. In Figure 7(a), initially the delay of the base case and the sleepy keeper inverter are different. However, as transistor width increases, sleepy keeper shows noticeable delay reduction, and the sleepy keeper and the base case achieve similar delay using 4 times transistor width, but the forced stack shows 26 times larger leakage power consumption than the sleepy keeper technique.





Figure 7: Results for Chain of Inverters, Varying Width at 270C a) Delay b) Static Power c) Dynamic Power

Experimental Results for Generic Logic Circuits

The Sleepy Keeper technique is compared with all the existing techniques in terms of delay, dynamic power, static power and area. In case of 45nm technologies the following results have been observed for Generic logic circuits like 4-bit adder, 4:1 Multiplexer, Chain of 4 Inverters. Figure 8 to 10 shows the graphs plotted in comparison with various technologies for delay, static power, dynamic power and area for the three test circuits.

In 45nm technology, for a 4-bit adder test circuit the sleepy keeper approach (with dual Vth) achieves 114 times leakage reduction over the base case. The result is similar to the previous best leakage reduction technique with state saving, sleepy stack, but sleepy keeper achieves less delay than sleepy stack i.e. 43% less delay than sleepy stack with single Vth and 46% less delay with dual Vth. But Sleepy keeper consumes more dynamic power than sleepy stack. The area usage of the sleepy keeper is 76% smaller than area usage of the sleepy stack.

In case of 4:1 Multiplexer test circuit the Sleepy keeper approach (with dual Vth) achieves 140 times leakage reduction over the base case and when compared to sleepy stack the result is almost similar but however sleepy keeper achieves 42% less delay than sleepy stack with single Vth and 45% less delay with dual Vth. The area usage for sleepy keeper is 35% smaller than the area usage of the sleepy stack.

For a Chain of 4 inverters test circuit the keeper approach with dual Vth achieves 115 times leakage reduction over the base case and when compared to the stack approach it achieves 17 times leakage reduction. The sleepy keeper achieves less delay than the stack approach i.e. 53% less delay than the stack with single Vth and 35% less delay with dual Vth. The area usage of sleepy keeper is smaller than area usage of sleepy stack.



Figure 8: Results for 4 bit adder a) Delay b) Static Power c) Dynamic Power d) Area



Figure 9: Results for 4:1 Multiplexer a) Delay b) Static Power c) Dynamic Power d) Area



Figure 10: Results for Chain of 4 Inverters a) Delay b) Static Power c) Dynamic Power d) Area

Conclusions

In nanometer scale CMOS technology, sub-threshold leakage power is comparable to dynamic power consumption, and thus handling leakage power is a great challenge. A circuit structure named "sleepy keeper" is presented to tackle the leakage problem. Sleepy keeper uses traditional sleep transistors plus two additional transistors driven by a gate's already calculated output to save state during sleep mode. Dual Vth values applied to sleepy keeper in order to dramatically reduce sub-threshold leakage current. Like the sleepy stack approach, sleepy keeper achieves leakage power reduction equivalent to the sleep and zigzag approaches but with the advantage of maintaining exact logic state (instead of destroying the logic state when sleep mode is entered).

The sleepy keeper technique can retain logic state, so it can be used for both generic logic circuits as well as memory, i.e., SRAM. When applied to generic logic circuits, the sleepy keeper technique achieves up to 110-150 times leakage reduction compared the stack technique with up to 25% delay reduction and 75 - 110% area overhead.

The sleepy keeper has significant impact on low-power VLSI design. For systems spending a large percentage of time in sleep mode yet requiring ultra-fast wakeup through maintenance of precise logic state, sleepy keeper may provide the best solution.

The sleepy keeper approach causes dynamic power increase which seems to be the main disadvantage of the approach. The increase is most likely due to placing an NMOS transistor in a pull-up network and a PMOS transistor in a pull-down network where the two added transistors are controlled by the output voltage.

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